

Notes: 1.All dimensions are in millimeters
2.Tolerances unless dimensions $\pm 0.15\text{mm}$

Absolute Maximum Ratings (Ta=25°C)

Parameter		Symbol	Ratings	Unit
Input	Power Dissipation at(or below) 25°C Free Air Temperature	Pd	75	mW
	Reverse Voltage	V _R	5	V
	Forward Current	I _F	50	mA
	Peak Forward Current (*1) Pulse width ≤ 100 μs, Duty cycle=1%	I _{FP}	1	A
Output	Collector Power Dissipation	P _C	75	mW
	Collector Current	I _C	50	mA
	Collector-Emitter Voltage	B V _{CEO}	30	V
	Emitter-Collector Voltage	B V _{ECO}	5	V
Operating Temperature		Topr	-25~+85	°C
Storage Temperature		Tstg	-30~+90	°C
Lead Soldering Temperature (*2)		Tsol	260	°C

(* 1) tw=100 μ sec. , T=10 msec. (* 2) t=5 Sec

Electro-Optical Characteristics (Ta=25°C)

Parameter		Symbol	Min.	Typ.	Max.	Unit	Conditions
Input	Forward Voltage	V _F	---	1.2	1.6	V	I _F =20mA
	Reverse Current	I _R	---	---	10	μ A	V _R =5V
	Peak Wavelength	λ _p	---	940	---	nm	---
Output	Dark Current	I _{CEO}	---	---	100	nA	V _{CE} =10V
	C-E Saturation Voltage	V _{CE(sat)}	---	---	0.4	V	I _C =2mA ,Ee=1mW/cm ²
Transfer Characteristics	Light Current	I _{C(ON)}	0.1	---	---	mA	V _{CE} =5V
	Leakage Current	I _{CEOD}	---	---	1	μ A	I _F =20mA
	Rise time	t _r	---	20	---	μ sec	V _{CE} =2V
	Fall time	t _f	---	20	---	μ sec	I _C =100 μ A R _L =1KΩ

Typical Electrical/Optical/Characteristics Curves for IR

Fig. 1 Forward Current vs. Ambient Temperature

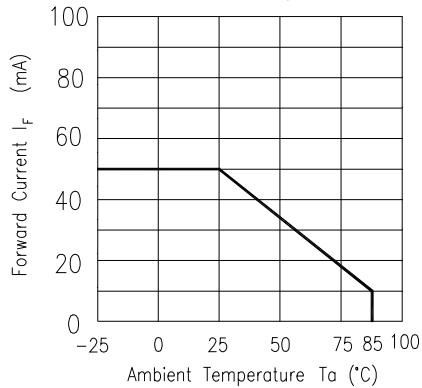


Fig. 2 Spectral Distribution

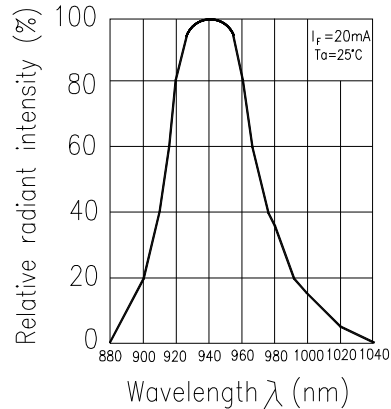


Fig. 3 Peak Emission Wavelength vs. Ambient Temperature

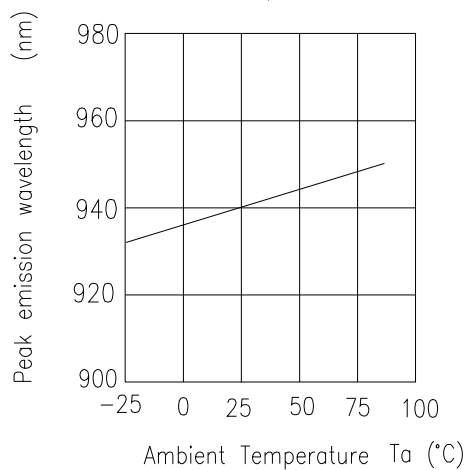


Fig. 4 Forward Current vs. Forward Voltage

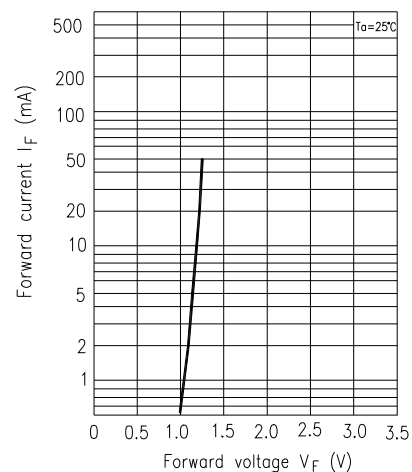


Fig. 5 Forward Voltage vs. Ambient Temperature

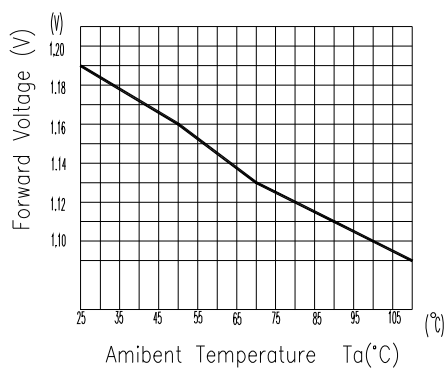
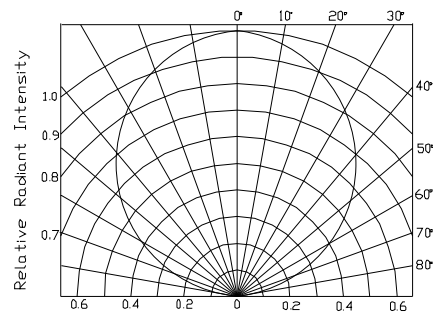


Fig. 6 Relative Radiant Intensity vs. Angular Displacement



Typical Electro/Optical/Characteristics Curves for PT

Fig.1 Collector Power Dissipation vs. Ambient Temperature

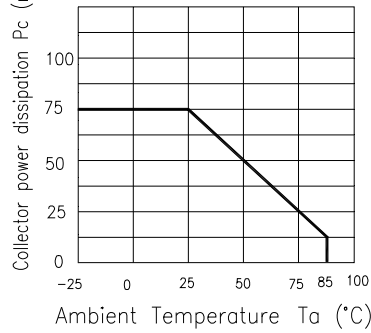


Fig.2 Collector Dark Current vs. Ambient Temperature

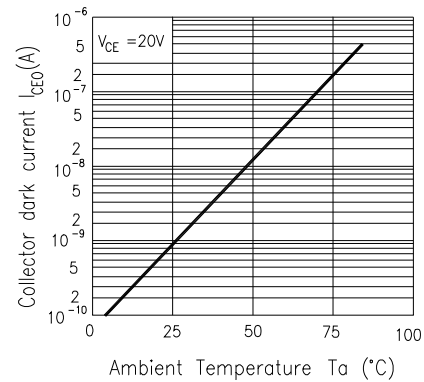


Fig. 3 Relative Collector Current vs. Ambient Temperature

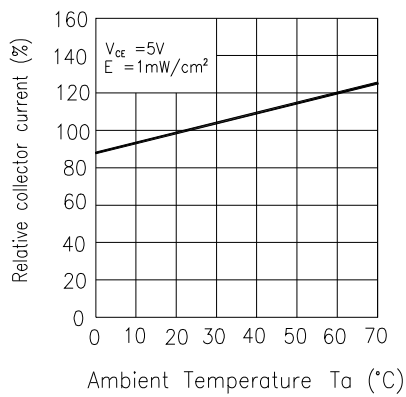


Fig.4 Collector Current vs. Irradiance

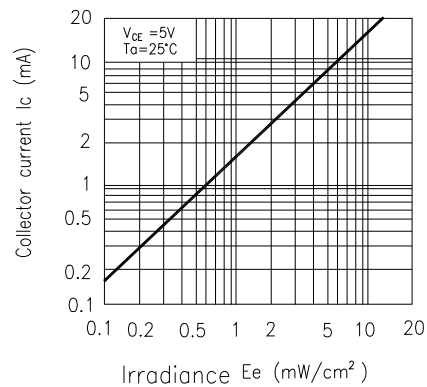


Fig.5 Spectral Sensitivity

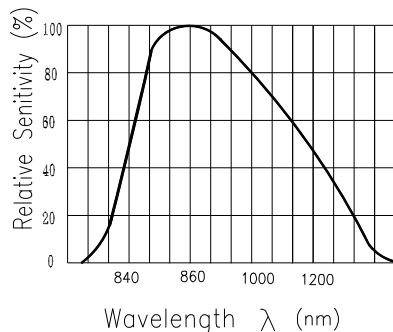
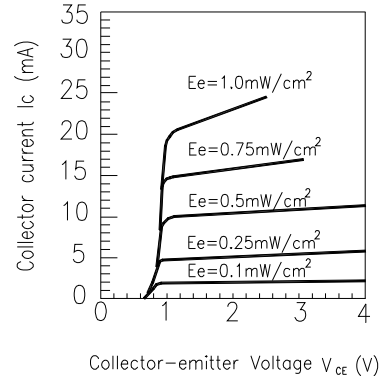


Fig.6 Collector Current vs. Collector-emitter Voltage



Typical Electrical/Optical/Characteristics Curves For ITR

Fig.1 Relative Collector Current vs. Distance between Sensor and Al Evaporation Galss

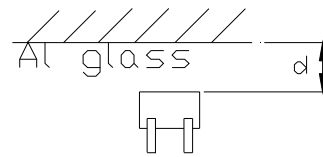
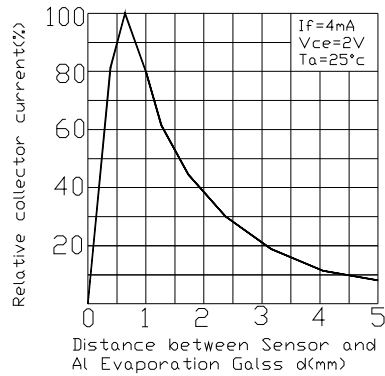


Fig.2 Relative Collector Current vs. Card Moving Distance (l)

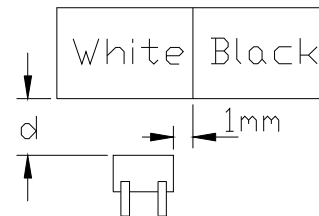
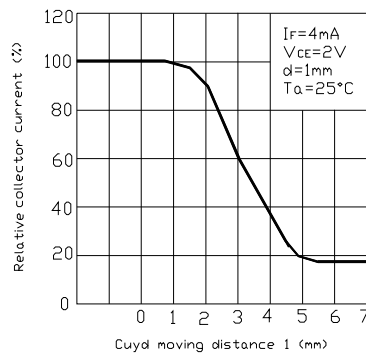
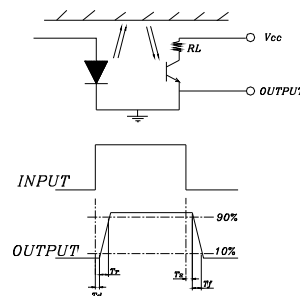
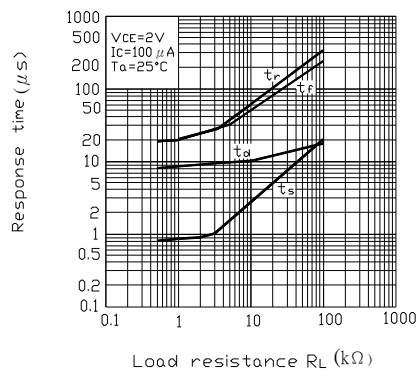
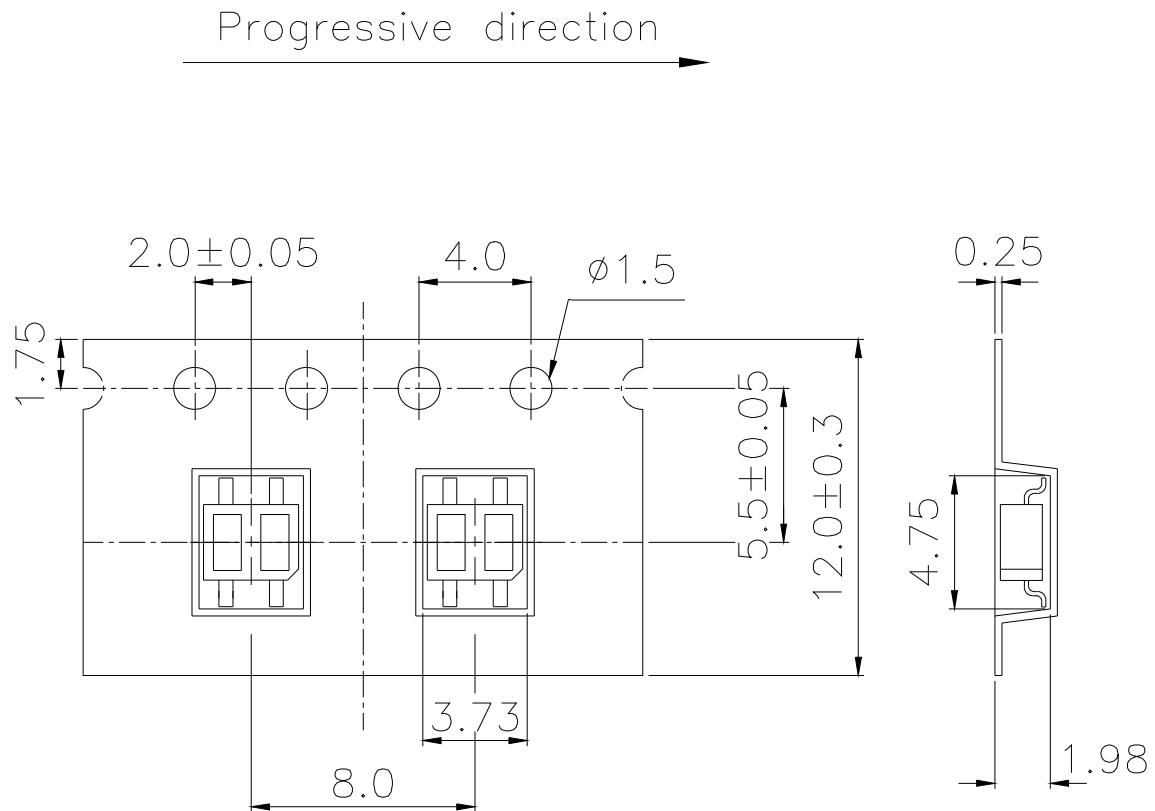


Fig.3 Response Time vs. Load Resistance



■ Taping Dimension



General Tolerance ± 0.1
UNIT:mm

Packing Quantity

1. 1000 Pcs/ 1Roll
2. 15roll /1 Box
3. 2 Box/ 1 Carton

Reliability Test Item And Condition

The reliability of products shall be satisfied with items listed below.

Confidence level : 90%

LTPD : 10%

NO.	Item	Test Conditions	Test Hours/ Cycles	Sample Sizes	Failure Judgement Criteria	Ac/Re
1	Solder Heat	TEMP. : $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$	10secs	22pcs	$I_R \geq U \times 2$ $E_e \leq L \times 0.8$ $V_F \geq U \times 1.2$ U : Upper Specification Limit L : Lower Specification Limit	0/1
2	Temperature Cycle	H : $+85^{\circ}\text{C}$ 30mins \updownarrow 5mins L : -55°C 30mins	50Cycles	22pcs		0/1
3	Thermal Shock	H : $+100^{\circ}\text{C}$ 5mins \updownarrow 10secs L : -10°C 5mins	50Cycles	22pcs		0/1
4	High Temperature Storage	TEMP. : $+100^{\circ}\text{C}$	1000hrs	22pcs		0/1
5	Low Temperature Storage	TEMP. : -55°C	1000hrs	22pcs		0/1
6	DC Operating Life	$I_F = 20\text{mA}$	1000hrs	22pcs		0/1
7	High Temperature/ High Humidity	85°C / 85% R.H	1000hrs	22pcs		0/1

Recommended Method of Storage

The following are general recommendations for moisture sensitive level (MSL) 4 storage and use:

- Shelf life in sealed bag: 12 months at $< 40^{\circ}\text{C}$ and $< 90\%$ relative humidity (RH)
- After bag is opened, devices that will be subjected to reflow solder or other high temperature process must
 - a) Mounted within 72 hours of factory conditions $< 30^{\circ}\text{C}/60\%\text{RH}$, or
 - b) Stored at $< 20\%\text{RH}$
 - Devices require bake, before mounting, if:
Humidity Indicator Card is $> 20\%$ when read at $23 \pm 5^{\circ}\text{C}$
- If baking is required, devices may be baked:
 - a) 192 hours at 40°C , and $< 5\%\text{RH}$ (dry air/nitrogen) or
 - b) 96 hours at 60°C , and $< 5\%\text{RH}$ for all device containers
 - c) 24 hours at 125°C

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